

CY54FCT245T, CY74FCT245T 8-BIT TRANSCEIVERS WITH 3-STATE OUTPUTS

SCCS018B – MAY 1994 – REVISED NOVEMBER 2001

- Function, Pinout, and Drive Compatible With FCT and F Logic
- Reduced V_{OH} (Typically = 3.3 V) Versions of Equivalent FCT Functions
- Edge-Rate Control Circuitry for Significantly Improved Noise Characteristics
- I_{off} Supports Partial-Power-Down Mode Operation
- ESD Protection Exceeds JESD 22
 - 2000-V Human-Body Model (A114-A)
 - 200-V Machine Model (A115-A)
 - 1000-V Charged-Device Model (C101)
- Matched Rise and Fall Times
- Fully Compatible With TTL Input and Output Logic Levels
- CY54FCT245T
 - 48-mA Output Sink Current
 - 12-mA Output Source Current
- CY74FCT245T
 - 64-mA Output Sink Current
 - 32-mA Output Source Current
- 3-State Outputs

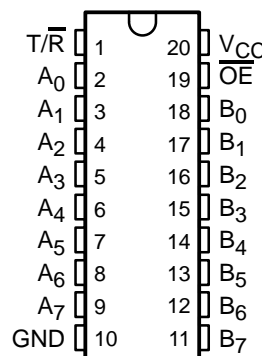
description

The 'FCT245T devices contain eight noninverting bidirectional buffers with 3-state outputs and are intended for bus-oriented applications.

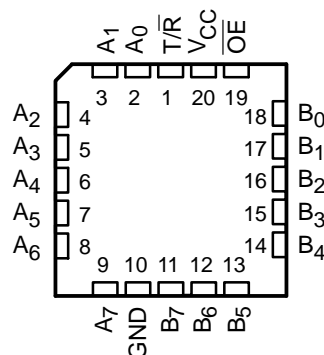
The transmit/receive (T/\bar{R}) input determines the direction of data flow through these bidirectional transceivers. Transmit (active high) enables data from A ports to B ports. The output enable (\overline{OE}), when high, disables both the A and B ports by putting them in the high-impedance state.

These devices are fully specified for partial-power-down applications using I_{off} . The I_{off} circuitry disables the outputs, preventing damaging current backflow through the device when it is powered down.

CY54FCT245T . . . D PACKAGE
CY74FCT245T . . . P, Q, OR SO PACKAGE
(TOP VIEW)



CY54FCT245T . . . L PACKAGE
(TOP VIEW)



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PRODUCTION DATA information is current as of publication date. Products conform to specifications per the terms of Texas Instruments standard warranty. Production processing does not necessarily include testing of all parameters.

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WITH 3-STATE OUTPUTS

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ORDERING INFORMATION

T _A	PACKAGE†		SPEED (ns)	ORDERABLE PART NUMBER	TOP-SIDE MARKING
-40°C to 85°C	QSOP – Q	Tape and reel	3.8	CY74FCT245DTQCT	FCT245D
	QSOP – Q	Tape and reel	4.1	CY74FCT245CTQCT	FCT245C
	SOIC – SO	Tube	4.1	CY74FCT245CTSOC	FCT245C
		Tape and reel	4.1	CY74FCT245CTSOCT	
	DIP – P	Tube	4.6	CY74FCT245ATPC	CY74FCT245ATPC
	QSOP – Q	Tape and reel	4.6	CY74FCT245ATQCT	FCT245A
	SOIC – SO	Tube	4.6	CY74FCT245ATSOC	FCT245A
		Tape and reel	4.6	CY74FCT245ATSOCT	
	QSOP – Q	Tape and reel	7	CY74FCT245TQCT	FCT245
SOIC – SO	Tube	7	CY74FCT245TSOC	FCT245	
	Tape and reel	7	CY74FCT245TSOCT		
-55°C to 125°C	CDIP – D	Tube	4.5	CY54FCT245CTDMB	
	LCC – L	Tube	4.5	CY54FCT245CTLMB	
	CDIP – D	Tube	4.9	CY54FCT245ATDMB	
	LCC – L	Tube	4.9	CY54FCT245ATLMB	
	CDIP – D	Tube	7.5	CY54FCT245TDMB	
	LCC – L	Tube	7.5	CY54FCT245TLMB	

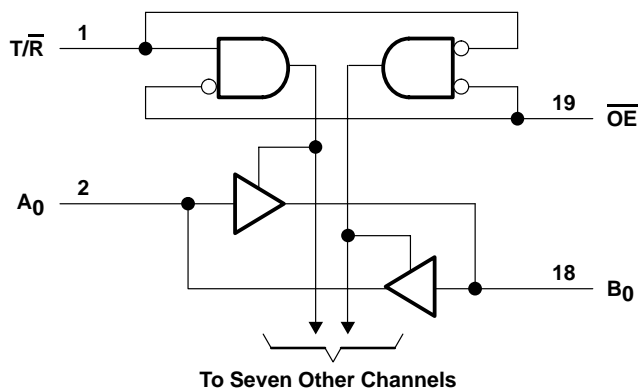
† Package drawings, standard packing quantities, thermal data, symbolization, and PCB design guidelines are available at www.ti.com/sc/package.

FUNCTION TABLE

INPUTS		OPERATION
\overline{OE}	T/R	
L	L	B data to bus A
L	H	A data to bus B
H	X	Z

H = High logic level, L = Low logic level,
 X = Don't care, Z = High-impedance state

logic diagram (positive logic)



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS	CY54FCT245T			CY74FCT245T			UNIT
		MIN	TYP†	MAX	MIN	TYP†	MAX	
V _{IK}	V _{CC} = 4.5 V, I _{IN} = -18 mA	-0.7	-1.2					V
	V _{CC} = 4.75 V, I _{IN} = -18 mA				-0.7	-1.2		
V _{OH}	V _{CC} = 4.5 V, I _{OH} = -12 mA	2.4	3.3					V
	V _{CC} = 4.75 V	I _{OH} = -32 mA			2			
		I _{OH} = -15 mA			2.4	3.3		
V _{OL}	V _{CC} = 4.5 V, I _{OL} = 48 mA	0.3	0.55					V
	V _{CC} = 4.75 V, I _{OL} = 64 mA				0.3	0.55		
V _{hys}	All inputs	0.2			0.2			V
I _I	V _{CC} = 5.5 V, V _{IN} = V _{CC}			5				μA
	V _{CC} = 5.25 V, V _{IN} = V _{CC}					5		
I _{IH}	V _{CC} = 5.5 V, V _{IN} = 2.7 V			±1				μA
	V _{CC} = 5.25 V, V _{IN} = 2.7 V					±1		
I _{IL}	V _{CC} = 5.5 V, V _{IN} = 0.5 V			±1				μA
	V _{CC} = 5.25 V, V _{IN} = 0.5 V					±1		
I _{OZH}	V _{CC} = 5.5 V, V _{OUT} = 2.7 V			10				μA
	V _{CC} = 5.25 V, V _{OUT} = 2.7 V					10		
I _{OZL}	V _{CC} = 5.5 V, V _{OUT} = 0.5 V			-10				μA
	V _{CC} = 5.25 V, V _{OUT} = 0.5 V					-10		
I _{OS} ‡	V _{CC} = 5.5 V, V _{OUT} = 0 V	-60	-120	-225				mA
	V _{CC} = 5.25 V, V _{OUT} = 0 V				-60	-120	-225	
I _{off}	V _{CC} = 0 V, V _{OUT} = 4.5 V			±1			±1	μA
I _{CC}	V _{CC} = 5.5 V, V _{IN} ≤ 0.2 V, V _{IN} ≥ V _{CC} - 0.2 V	0.1	0.2					mA
	V _{CC} = 5.25 V, V _{IN} ≤ 0.2 V, V _{IN} ≥ V _{CC} - 0.2 V				0.1	0.2		
ΔI _{CC}	V _{CC} = 5.5 V, V _{IN} = 3.4 V [§] , f ₁ = 0, Outputs open	0.5	2					mA
	V _{CC} = 5.25 V, V _{IN} = 3.4 V [§] , f ₁ = 0, Outputs open				0.5	2		
I _{CCD} [¶]	V _{CC} = 5.5 V, One input switching at 50% duty cycle, Outputs open, T/R or OE = GND and V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} - 0.2 V	0.06	0.12					mA/ MHz
	V _{CC} = 5.25 V, One input switching at 50% duty cycle, Outputs open, T/R or OE = GND and V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} - 0.2 V				0.06	0.12		

† Typical values are at V_{CC} = 5 V, T_A = 25°C.

‡ Not more than one output should be shorted at a time. Duration of short should not exceed one second. The use of high-speed test apparatus and/or sample-and-hold techniques are preferable to minimize internal chip heating and more accurately reflect operational values. Otherwise, prolonged shorting of a high output can raise the chip temperature well above normal and cause invalid readings in other parametric tests. In any sequence of parameter tests, I_{OS} tests should be performed last.

§ Per TTL-driven input (V_{IN} = 3.4 V); all other inputs at V_{CC} or GND

¶ This parameter is derived for use in total power-supply calculations.

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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted) (continued)

PARAMETER	TEST CONDITIONS			CY54FCT245T		CY74FCT245T		UNIT
				MIN	TYP†	MAX	MIN	
I _C #	V _{CC} = 5.5 V, Outputs open, T/R or OE = GND	One bit switching at f ₁ = 10 MHz at 50% duty cycle	V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V	0.7	1.4			mA
			V _{IN} = 3.4 V or GND	1.2	3.4			
		Eight bits switching at f ₁ = 2.5 MHz at 50% duty cycle	V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V	1.3	2.6			
			V _{IN} = 3.4 V or GND	3.3	10.6			
	V _{CC} = 5.25 V, Outputs open, T/R or OE = GND	One bit switching at f ₁ = 10 MHz at 50% duty cycle	V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V			0.7	1.4	
			V _{IN} = 3.4 V or GND			1.2	3.4	
		Eight bits switching at f ₁ = 2.5 MHz at 50% duty cycle	V _{IN} ≤ 0.2 V or V _{IN} ≥ V _{CC} – 0.2 V			1.3	2.6	
			V _{IN} = 3.4 V or GND			3.3	10.6	
C _i				5	10	5	10	pF
C _o				9	12	9	12	pF

† Typical values are at V_{CC} = 5 V, T_A = 25°C.

I_C = I_{CC} + ΔI_{CC} × D_H × N_T + I_{CCD} (f₀/2 + f₁ × N₁)

Where:

I_C = Total supply current

I_{CC} = Power-supply current with CMOS input levels

ΔI_{CC} = Power-supply current for a TTL high input (V_{IN} = 3.4 V)

D_H = Duty cycle for TTL inputs high

N_T = Number of TTL inputs at D_H

I_{CCD} = Dynamic current caused by an input transition pair (HLH or LHL)

f₀ = Clock frequency for registered devices, otherwise zero

f₁ = Input signal frequency

N₁ = Number of inputs changing at f₁

All currents are in milliamperes and all frequencies are in megahertz.

|| Values for these conditions are examples of the I_{CC} formula.

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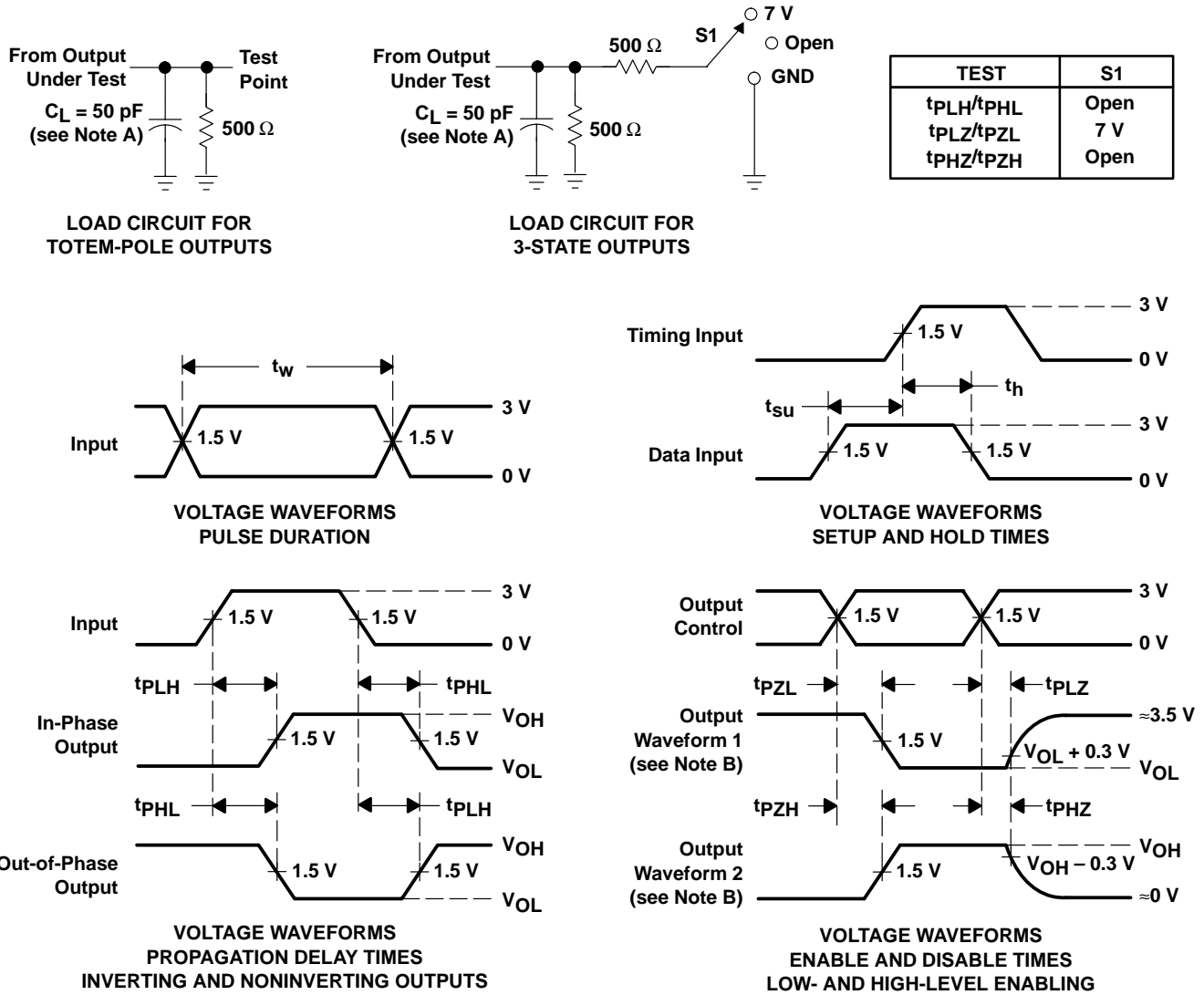
switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY54FCT245T		CY54FCT245AT		CY54FCT245CT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	1.5	7.5	1.5	4.9	1.5	4.5	ns
t _{PHL}			1.5	7.5	1.5	4.9	1.5	4.5	
t _{PZH}	\overline{OE} or T/ \overline{R}	A or B	1.5	10	1.5	6.5	1.5	6.2	ns
t _{PZL}			1.5	10	1.5	6.5	1.5	6.2	
t _{PHZ}	\overline{OE} or T/ \overline{R}	A or B	1.5	10	1.5	6	1.5	5.2	ns
t _{PLZ}			1.5	10	1.5	6	1.5	5.2	

switching characteristics over operating free-air temperature range (see Figure 1)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	CY74FCT245T		CY74FCT245AT		CY74FCT245CT		CY74FCT245DT		UNIT
			MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{PLH}	A or B	B or A	1.5	7	1.5	4.6	1.5	4.1	1.5	3.8	ns
t _{PHL}			1.5	7	1.5	4.6	1.5	4.1	1.5	3.8	
t _{PZH}	\overline{OE} or T/ \overline{R}	A or B	1.5	9.5	1.5	6.2	1.5	5.8	1.5	5	ns
t _{PZL}			1.5	9.5	1.5	6.2	1.5	5.8	1.5	5	
t _{PHZ}	\overline{OE} or T/ \overline{R}	A or B	1.5	7.5	1.5	5	1.5	4.8	1.5	4.3	ns
t _{PLZ}			1.5	7.5	1.5	5	1.5	4.8	1.5	4.3	

PARAMETER MEASUREMENT INFORMATION



- NOTES: A. C_L includes probe and jig capacitance.
 B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 C. The outputs are measured one at a time with one input transition per measurement.

Figure 1. Load Circuit and Voltage Waveforms

PACKAGING INFORMATION

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
5962-9221401M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9221401MRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
5962-9221403M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9221403MRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
5962-9221405M2A	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
5962-9221405MRA	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
CY54FCT245ATDMB	ACTIVE	CDIP	J	20	1	TBD	A42	N / A for Pkg Type
CY54FCT245CTLMB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
CY54FCT245TLMB	ACTIVE	LCCC	FK	20	1	TBD	POST-PLATE	N / A for Pkg Type
CY74FCT245ATPC	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CY74FCT245ATPCE4	ACTIVE	PDIP	N	20	20	Pb-Free (RoHS)	CU NIPDAU	N / A for Pkg Type
CY74FCT245ATQCT	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT245ATQCTE4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT245ATQCTG4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT245ATSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245ATSOCE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245ATSOCG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245ATSOCT	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245ATSOCTE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245ATSOCTG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245CTQCT	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT245CTQCTE4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT245CTQCTG4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT245CTSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245CTSOCE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245CTSOCG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245CTSOCT	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245CTSOCTE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245CTSOCTG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

Orderable Device	Status ⁽¹⁾	Package Type	Package Drawing	Pins	Package Qty	Eco Plan ⁽²⁾	Lead/Ball Finish	MSL Peak Temp ⁽³⁾
						no Sb/Br)		
CY74FCT245DTQCT	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT245DTQCTE4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT245DTQCTG4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT245TQCT	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT245TQCTE4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT245TQCTG4	ACTIVE	SSOP/ QSOP	DBQ	20	2500	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-2-260C-1 YEAR
CY74FCT245TSOC	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245TSOCE4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245TSOCG4	ACTIVE	SOIC	DW	20	25	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245TSOCT	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245TSOCTE4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM
CY74FCT245TSOCTG4	ACTIVE	SOIC	DW	20	2000	Green (RoHS & no Sb/Br)	CU NIPDAU	Level-1-260C-UNLIM

⁽¹⁾ The marketing status values are defined as follows:

ACTIVE: Product device recommended for new designs.

LIFEBUY: TI has announced that the device will be discontinued, and a lifetime-buy period is in effect.

NRND: Not recommended for new designs. Device is in production to support existing customers, but TI does not recommend using this part in a new design.

PREVIEW: Device has been announced but is not in production. Samples may or may not be available.

OBsolete: TI has discontinued the production of the device.

⁽²⁾ Eco Plan - The planned eco-friendly classification: Pb-Free (RoHS), Pb-Free (RoHS Exempt), or Green (RoHS & no Sb/Br) - please check <http://www.ti.com/productcontent> for the latest availability information and additional product content details.

TBD: The Pb-Free/Green conversion plan has not been defined.

Pb-Free (RoHS): TI's terms "Lead-Free" or "Pb-Free" mean semiconductor products that are compatible with the current RoHS requirements for all 6 substances, including the requirement that lead not exceed 0.1% by weight in homogeneous materials. Where designed to be soldered at high temperatures, TI Pb-Free products are suitable for use in specified lead-free processes.

Pb-Free (RoHS Exempt): This component has a RoHS exemption for either 1) lead-based flip-chip solder bumps used between the die and package, or 2) lead-based die adhesive used between the die and leadframe. The component is otherwise considered Pb-Free (RoHS compatible) as defined above.

Green (RoHS & no Sb/Br): TI defines "Green" to mean Pb-Free (RoHS compatible), and free of Bromine (Br) and Antimony (Sb) based flame retardants (Br or Sb do not exceed 0.1% by weight in homogeneous material)

⁽³⁾ MSL, Peak Temp. -- The Moisture Sensitivity Level rating according to the JEDEC industry standard classifications, and peak solder temperature.

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TAPE AND REEL INFORMATION



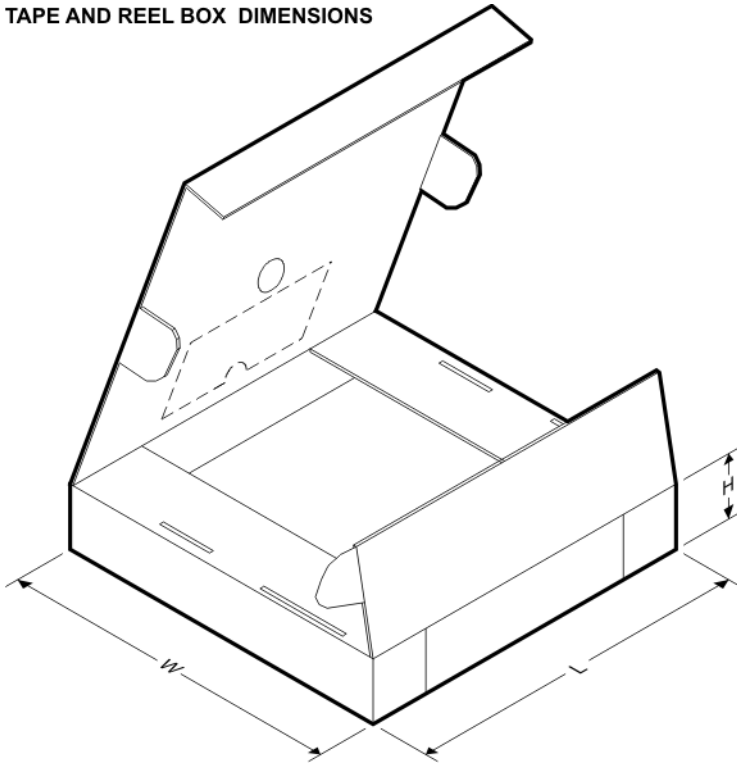
QUADRANT ASSIGNMENTS FOR PIN 1 ORIENTATION IN TAPE



*All dimensions are nominal

Device	Package Type	Package Drawing	Pins	SPQ	Reel Diameter (mm)	Reel Width W1 (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P1 (mm)	W (mm)	Pin1 Quadrant
CY74FCT245ATQCT	SSOP/QSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT245ATSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
CY74FCT245CTQCT	SSOP/QSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT245CTSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1
CY74FCT245DTQCT	SSOP/QSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT245TQCT	SSOP/QSOP	DBQ	20	2500	330.0	16.4	6.5	9.0	2.1	8.0	16.0	Q1
CY74FCT245TSOCT	SOIC	DW	20	2000	330.0	24.4	10.8	13.0	2.7	12.0	24.0	Q1

TAPE AND REEL BOX DIMENSIONS

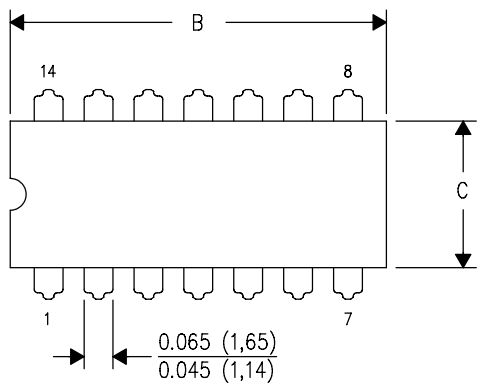


*All dimensions are nominal

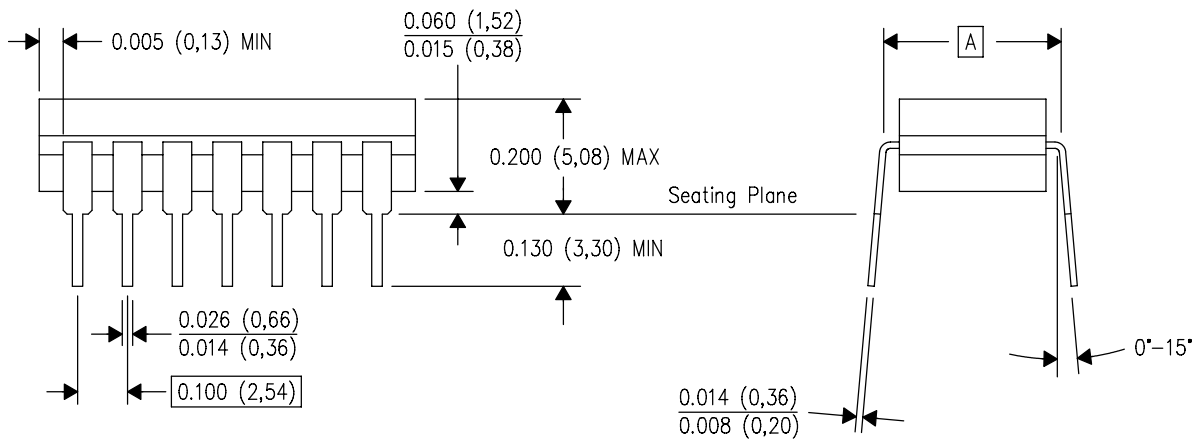
Device	Package Type	Package Drawing	Pins	SPQ	Length (mm)	Width (mm)	Height (mm)
CY74FCT245ATQCT	SSOP/QSOP	DBQ	20	2500	346.0	346.0	33.0
CY74FCT245ATSOCT	SOIC	DW	20	2000	346.0	346.0	41.0
CY74FCT245CTQCT	SSOP/QSOP	DBQ	20	2500	346.0	346.0	33.0
CY74FCT245CTSOCT	SOIC	DW	20	2000	346.0	346.0	41.0
CY74FCT245DTQCT	SSOP/QSOP	DBQ	20	2500	346.0	346.0	33.0
CY74FCT245TQCT	SSOP/QSOP	DBQ	20	2500	346.0	346.0	33.0
CY74FCT245TSOCT	SOIC	DW	20	2000	346.0	346.0	41.0

J (R-GDIP-T**)
14 LEADS SHOWN

CERAMIC DUAL IN-LINE PACKAGE



DIM \ PINS **	14	16	18	20
A	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC	0.300 (7,62) BSC
B MAX	0.785 (19,94)	.840 (21,34)	0.960 (24,38)	1.060 (26,92)
B MIN	—	—	—	—
C MAX	0.300 (7,62)	0.300 (7,62)	0.310 (7,87)	0.300 (7,62)
C MIN	0.245 (6,22)	0.245 (6,22)	0.220 (5,59)	0.245 (6,22)



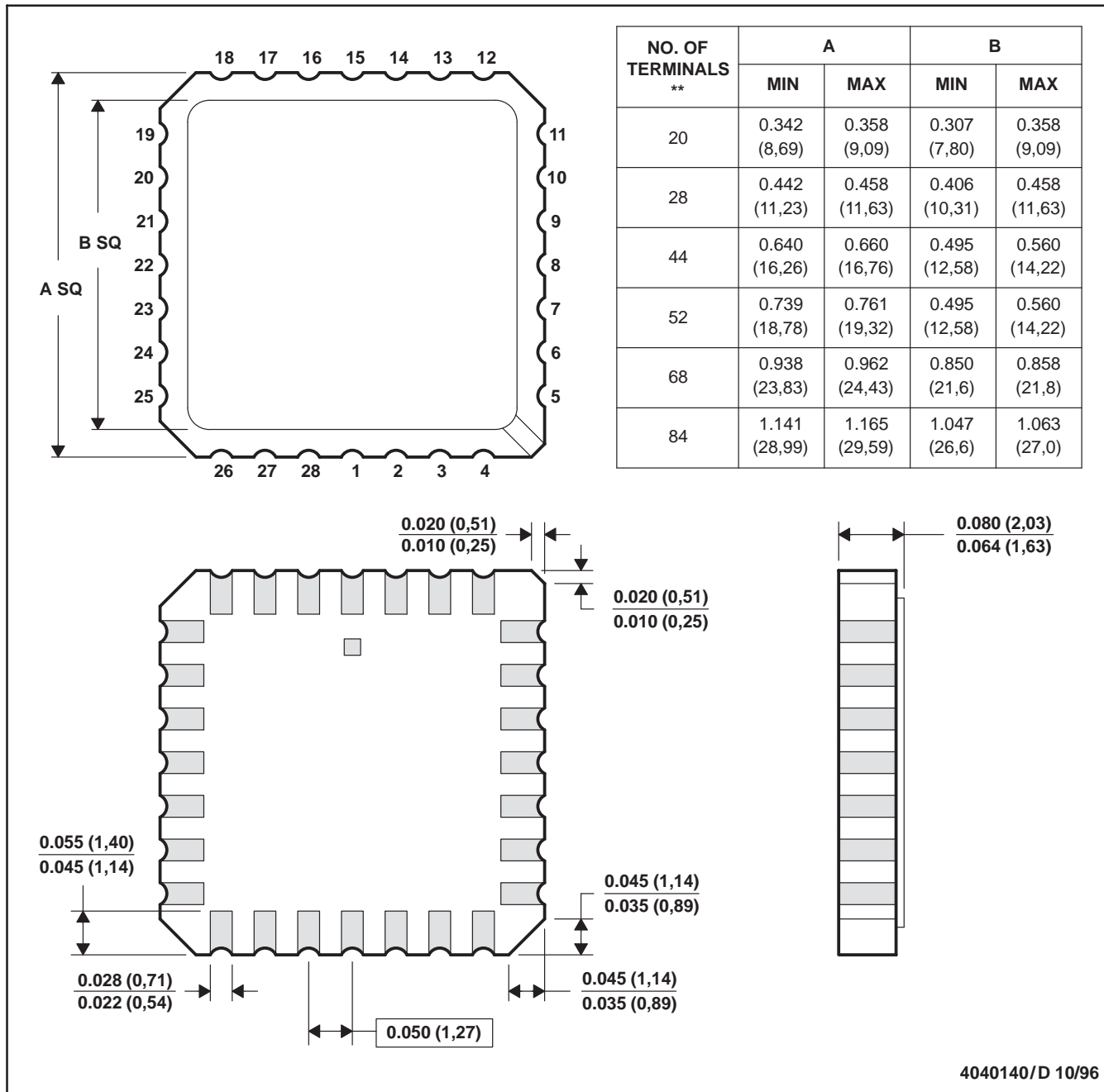
4040083/F 03/03

- NOTES:
- All linear dimensions are in inches (millimeters).
 - This drawing is subject to change without notice.
 - This package is hermetically sealed with a ceramic lid using glass frit.
 - Index point is provided on cap for terminal identification only on press ceramic glass frit seal only.
 - Falls within MIL STD 1835 GDIP1-T14, GDIP1-T16, GDIP1-T18 and GDIP1-T20.

FK (S-CQCC-N**)

LEADLESS CERAMIC CHIP CARRIER

28 TERMINAL SHOWN

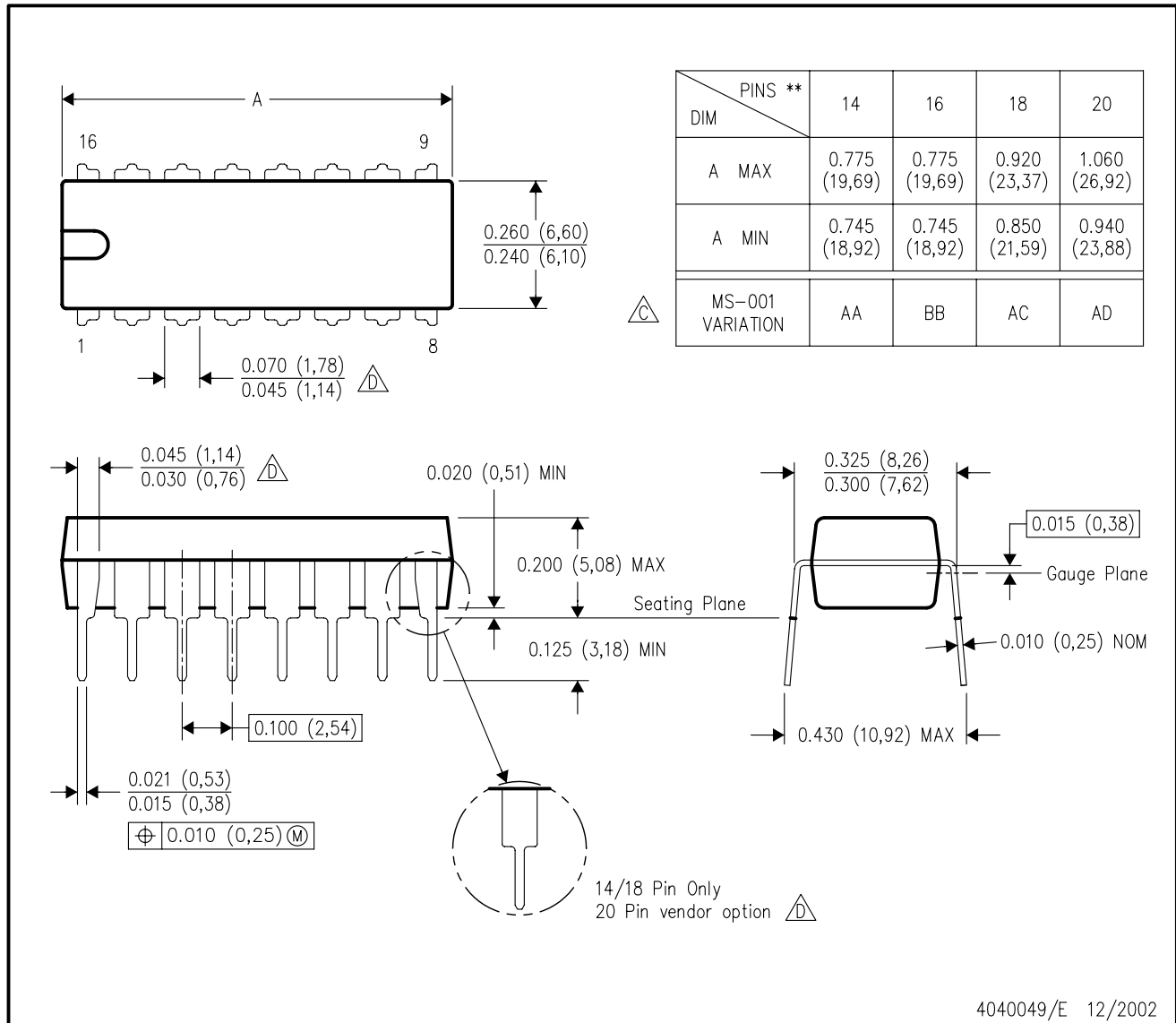


- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. This package can be hermetically sealed with a metal lid.
 - D. The terminals are gold plated.
 - E. Falls within JEDEC MS-004

N (R-PDIP-T**)

PLASTIC DUAL-IN-LINE PACKAGE

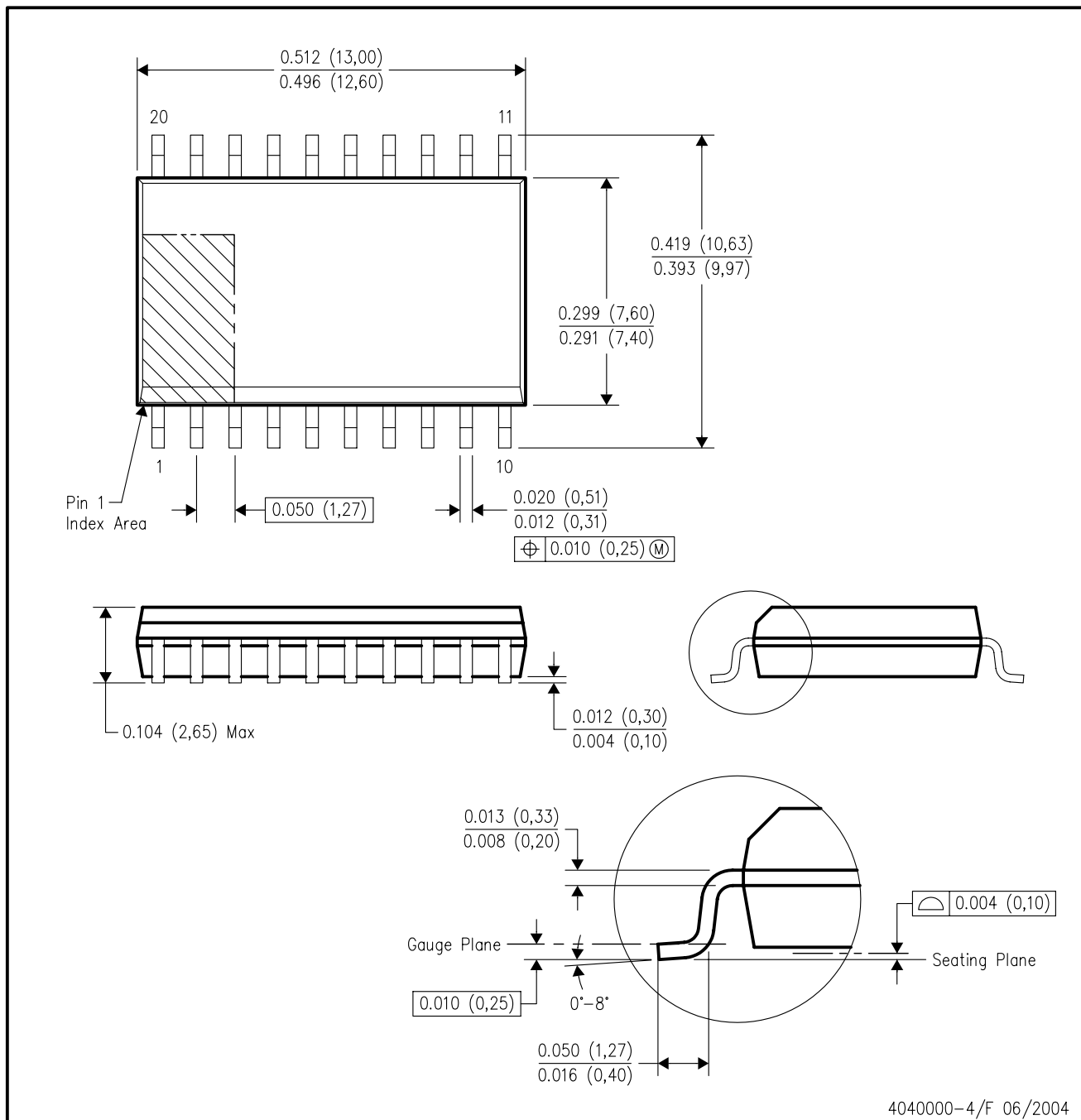
16 PINS SHOWN



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - Falls within JEDEC MS-001, except 18 and 20 pin minimum body length (Dim A).
 - The 20 pin end lead shoulder width is a vendor option, either half or full width.

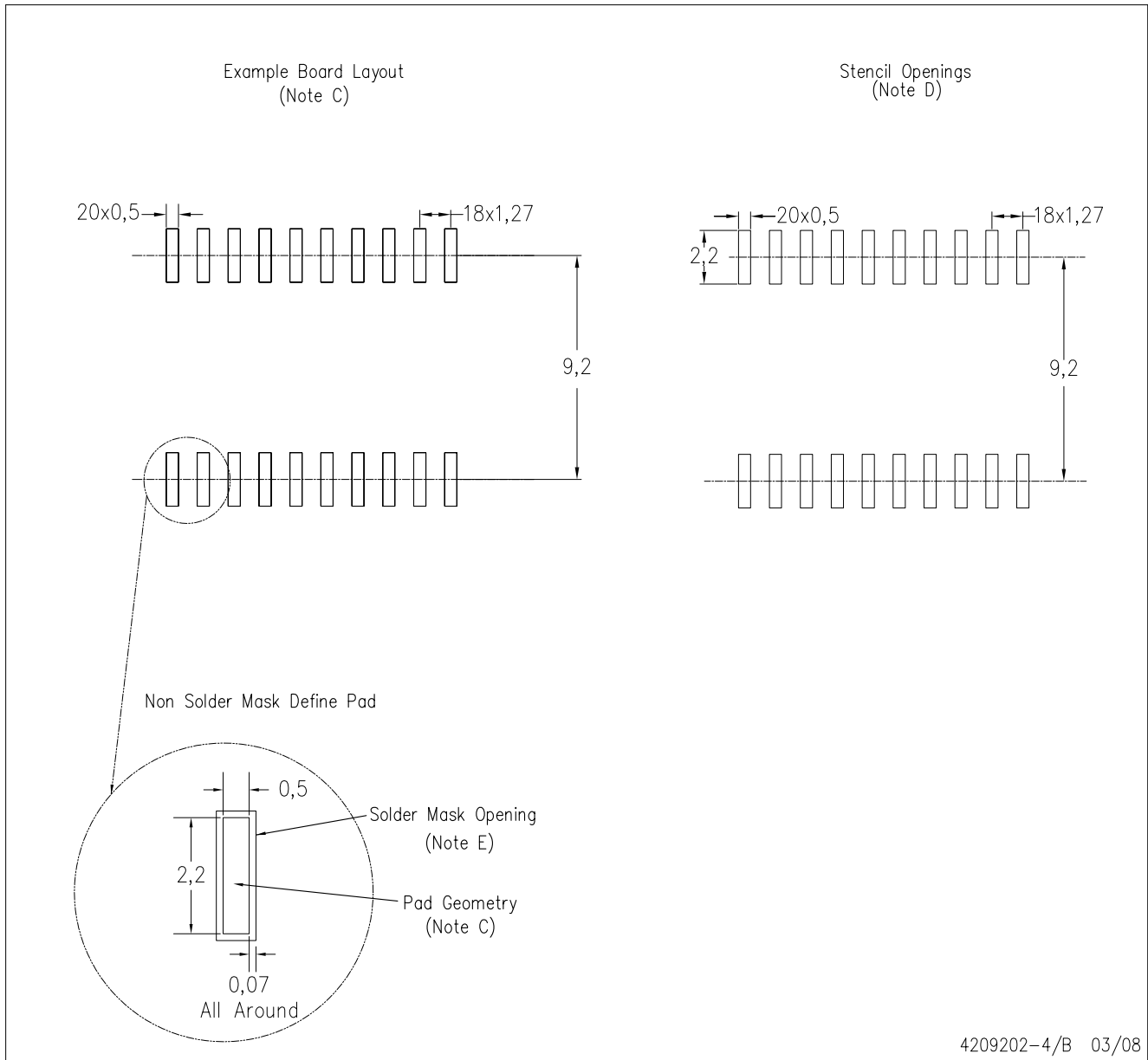
DW (R-PDSO-G20)

PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
 - D. Falls within JEDEC MS-013 variation AC.

DW (R-PDSO-G20)

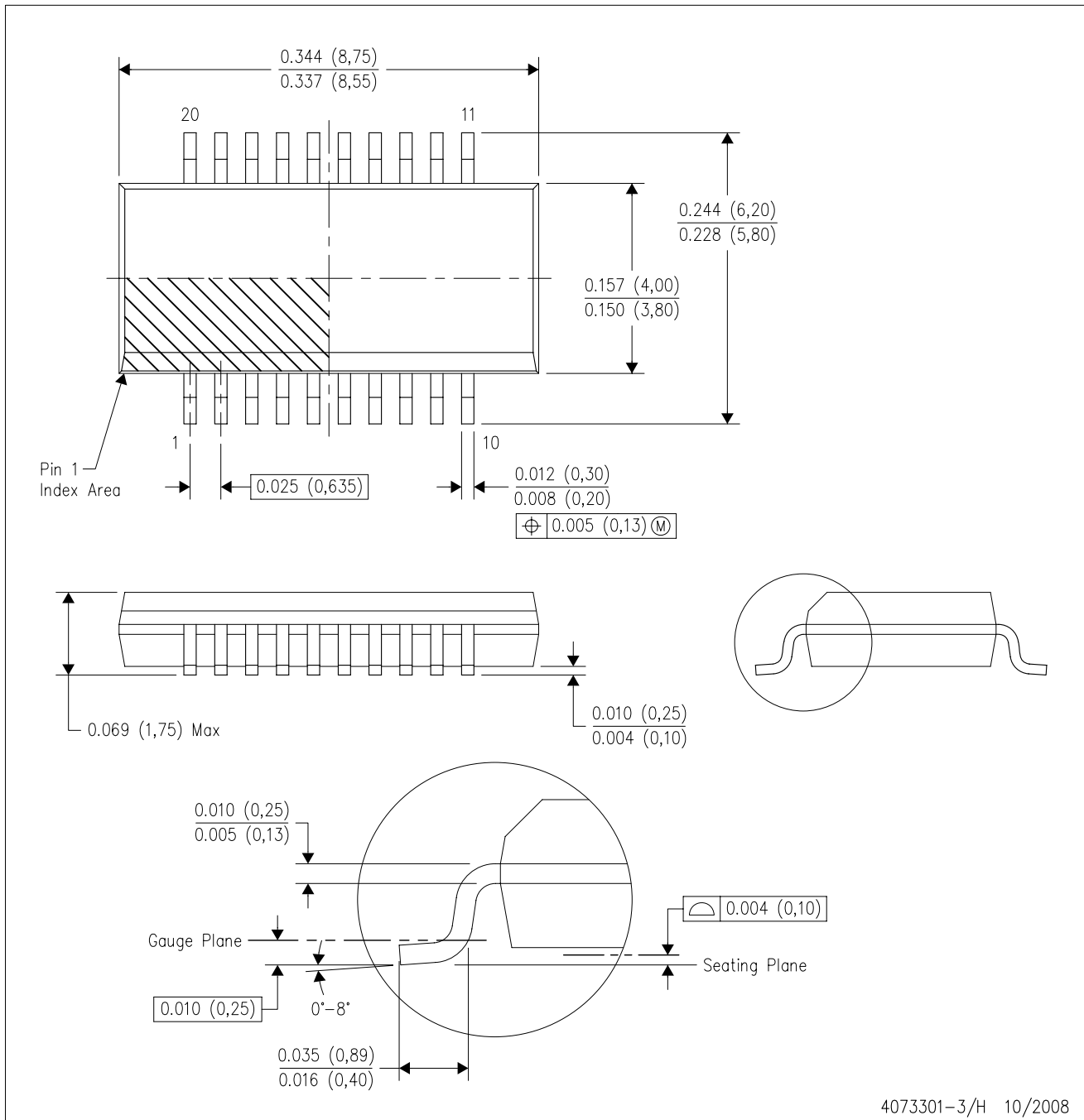


4209202-4/B 03/08

- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Refer to IPC-7525
 - E. Customers should contact their board fabrication site for solder mask tolerances between and around signal pads.

DBQ (R-PDSO-G20)

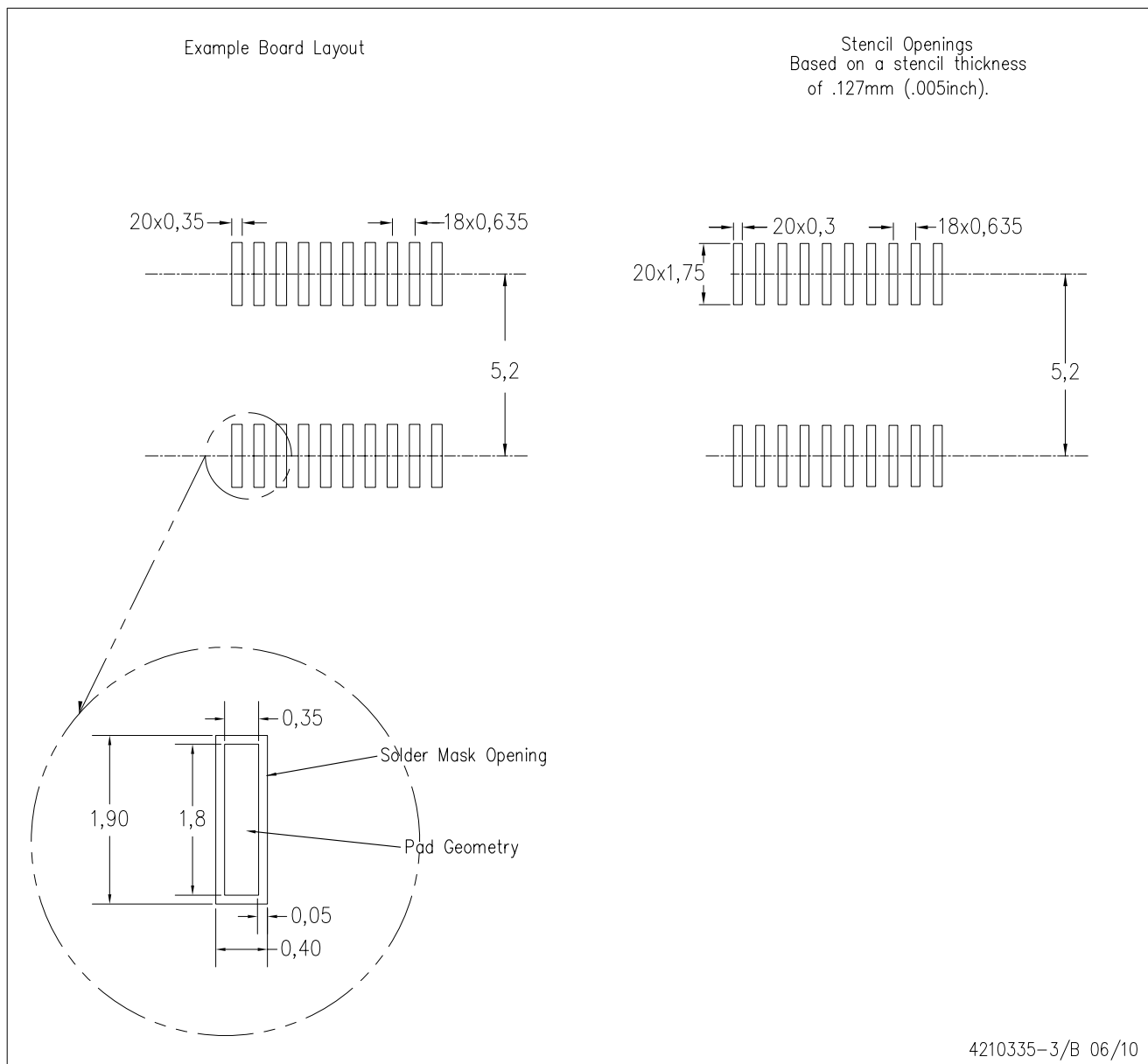
PLASTIC SMALL-OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in inches (millimeters).
 - B. This drawing is subject to change without notice.
 - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15) per side.
 - D. Falls within JEDEC MO-137 variation AD.

DBQ (R-PDSO-G20)

PLASTIC SMALL OUTLINE PACKAGE



- NOTES:
- A. All linear dimensions are in millimeters.
 - B. This drawing is subject to change without notice.
 - C. Customers should place a note on the circuit board fabrication drawing not to alter the center solder mask defined pad.
 - D. Publication IPC-7351 is recommended for alternate designs.
 - E. Laser cutting apertures with trapezoidal walls and also rounding corners will offer better paste release. Customers should contact their board assembly site for stencil design recommendations. Example stencil design based on a 50% volumetric metal load solder paste. Refer to IPC-7525 for other stencil recommendations.

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